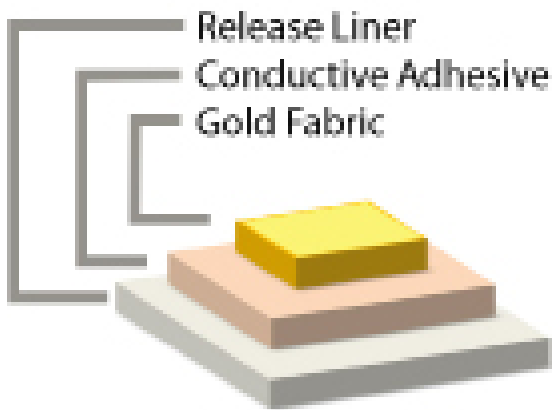




TGJGEA

Electrically Conductive Adhesive Tape

Version 3.120218



Electrically Conductive Adhesive Tape

TGJGEA is a double sided, isotropically conductive pressure sensitive tape which conducts electricity through the thickness (the Z-axis) and the plane of the adhesive (X, Y planes). Provides good adhesion and electrical performance.

Features

- Low outgassing acrylic adhesive
- Anisotropic Z-axis electrical conductivity
- PSA tack properties
- Thermal curing not required
- Easy to use in assembly operations
- Can be applied as die-cut parts or in roll form

Applications

- Antenna bonding and shielding
- EMI shielding
- Static dissipation

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Property	TGJGEA	Unit	Tolerance	Test Method
Colour	Gold	-	-	Visual
Thickness	0.05	mm	±0.01	Digital Up-right Gauge
Adhesive Force	800	gf/25mm	-	KSA1107
Surface Resistance	<0.1	Ω/in	-	Mil DTL 83528C
Top-Bottom Resistance	<0.1	Ω/in ²	-	Mil DTL 83528C
Using Temperature	-30 to 105	°C	-	ASTM D3330
Shelf Life (can be requalified for further 12)	12	months	-	-

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